



SCADA Security Scientific Symposium 2008

January 23 – 24 in Miami, FL

Call for Papers

General Information

Original papers on all technical aspects of SCADA and control system security are solicited for submission to the SCADA Security Scientific Symposium. This is a unique, highly technical conference for the control system security researcher and thought leaders. Papers must include significant original technical detail, and you will have time to present the detail to an audience that will understand. Submissions from research and academic institutions are encouraged. The symposium is organized by Digital Bond, Inc.

Some possible topics include vulnerability analysis of control system protocols, standards, devices and applications; methodologies and results of risk calculations; detecting and preventing attacks on control systems; performance impact of security on control systems; and whatever else a brilliant researcher can identify.

See examples of papers from S4 2007 at:

http://www.digitalbond.com/wp-content/uploads/2007/02/s4_overview2.pdf

Writer Benefits

- One hour presentation at S4 plus time for questions and answers
- Paper published in the S4 Proceedings Book provided to attendees and which will be available at digitalbond.com and amazon.com
- Hotel room provided by the symposium plus \$400 for travel expenses
- S4 registration fee waived
- Beautiful Miami in January (Conference hotel is right on the beach)

Submission Requirements

Submissions must include title, author(s), a short abstract, and summarize the new technical detail in the proposed paper. Final papers will be limited to 25 pages including references and appendices. If you would like to discuss a potential paper or know of a researcher you would recommend for S4 2008 send an email to S4@digitalbond.com.

Abstracts Submissions Due: Sept 15, 2007 (early submission improves odds of acceptance)

Acceptance Notification: October 1, 2007

Final Paper Due: December 1, 2007

Conference Dates: January 23 – 24, 2008 in Miami, FL

Submit Abstracts To S4@digitalbond.com